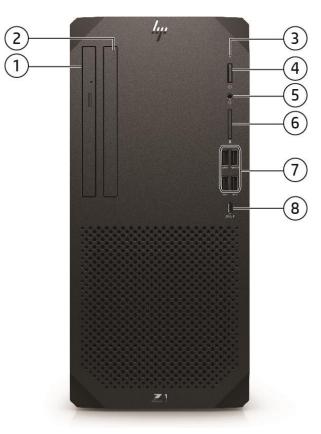
Overview

HP Z1 G9 Tower Desktop PC



- 1. Slim optical drive bay (optional)
- 2. Slim optical bay for removable 2.5" HDD or M.2 SSD (optional)
- 3. Hard drive activity light
- 4. Dual-state power button
- 5. Combo Audio Jack with CTIA and OMTP headset support

<u>Not Shown</u>

Slots

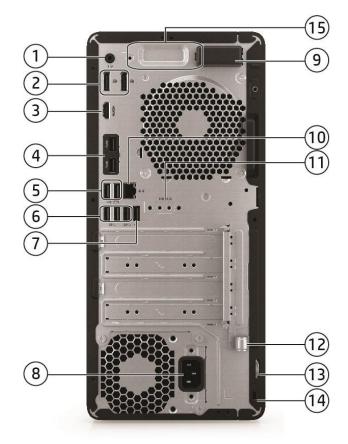
PCI Express Gen4 x16 (wired as x4)
 PCI Express 3.0 x 16 (wired as x4)
 PCI Express 3.0 x1
 M.2 (1 as M.2 2230 socket for WLAN/BT and 2 as M.2 2280 socket for storage)

- 6. SD card 4.0 reader (optional)
- (4) Type-A SuperSpeed USB 10Gbps signaling rate port (1 with charge support up to 5V/1.5A)
- 8. Type-C[®] SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)



Overview

HP Z1 G9 Tower Desktop PC



- Audio line-out jack connector 1.
- (2) Dual-Mode DisplayPort[™] 1.4 (DP++) 2.
- 3. HDMI port 1.4
- Flex port, choice of (shown here HDMI installed): 4.
 - DisplayPort[™] 1.4 • Dual Type-A SuperSpeed USB
 - HDMI 2.0b 5Gbps signaling rate port
 - VGA Serial
 - USB-C[®] SuperSpeed USB 10Gbps signaling rate port (USB-C[®] option has alt mode DisplayPort[™] 1.4 and 15W output)
- 5. (2) Type A Hi-Speed USB 480 Mbps signaling rate port with 15. External WLAN antenna (shown here not install) wake from S4/S5

Not shown

Optional ports

Thunderbolt[™] 3 card¹ PS/2 & serial port card (connected to mainboard via a flyer cable)¹

Parallel Port¹

1. Each of the legacy options will occupy one rear slot.

- (3) Type A SuperSpeed USB 5Gbps signaling rate port 6.
- 7. (1) Type A Hi-Speed USB 480 Mbps signaling rate port
- 8. Power cord connector
- 9. Internal WLAN antenna (optional, shown here installed)
- 10. RJ-45 (network) jack
- 11. Serial port (optional, not shown)
- 12. Integrated keyboard/mouse wire hoop
- 13. Pad Lock Loop
- 14. Standard cable lock slot

Bays

(2) 3.5" internal storage drive bay (2) Slim optical drive bay (optional, ODD and removable storage)

hD

Not all configuration components are available in all regions/countries. c08112669– DA 17011– Worldwide – Version 18 – March 18. 2024

Features

AT A GLANCE

- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability, and software image stability
- Intel[®] Q670 chipset supporting Intel[®] 12th generation Core[™] processors, featuring integrated Intel[®] UHD Graphics and Intel[®] vPro[®] Technology (available with Core i5- and above processors)
- Intel[®] Ethernet Connection I219LM GbE LOM integrated network connection
- Intel[®] Wi-Fi 7, Wi-Fi 6E + BT5.2 (802.11AX 2x2)⁵
- DDR5 Synchronous Dynamic Random Access Memory (SDRAM) up to 4400 MT/s
- Support for up to 8 monitors via two standard DisplayPort[™] 1.4 ports, HDMI 1.4, and a configurable Flex I/O port for video options and a discrete graphics
- Configurable FlexPort which provides the following choices: HDMI 2.0b, Serial, VGA, DisplayPort[™] 1.4, or USB Type-C[®] with DisplayPort[™] 1.4 Thunderbolt 3 (PCIe card, Thunderbolt 3 with USB4.0 (and Dual USB Type-A. See Ports section for port availability
- Configurable, NVIDIA[®] GeForce[®] VR ready and NVIDIA[®] Quadro[®] discrete graphics¹
- Can be configured with multiple data drives in a RAID array
- Enhanced Security with HP Security Suite (Refer to Security Section for details)
- ENERGY STAR[®] certified. EPEAT[®] registered where applicable. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit http://www.epeat.net for more information.
- CCC, CECP and SEPA Certified
- TCO Edge for All-in-One TCO
- PC chassis and all internal components and modules are manufactured with low halogen content
- Dust filter available
- Protected by HP Services, including limited warranties of 90/90/90, 1/1/1 and 3/3/3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 /UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

1. VR Ready is an optional feature which requires supported discrete graphics.

NOTE: See important legal disclosures for all listed specs in their respective feature sections

PRODUCT NAME

HP Z1 G9 Tower Desktop PC

OPERATING SYSTEM

Preinstalled	Windows 11 Pro ² Windows 11 Pro Education ²
	Windows 11 Home - HP recommends Windows 11 Pro for business ²
	Windows 11 Home Single Language - HP recommends Windows 11 Pro for business ²
	Windows 11 Pro (preinstalled with Windows 10 Pro Downgrade) ^{1,2,3}
	FreeDOS

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.



Features

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

CHIPSET

Intel[®] Q670



Features

PROCESSORS

Name	Ghz P- Core Base Frequenc Y	Ghz E- Core Base Frequenc y	Core Max	Up to x GHz E-Core Max Turbo Frequency	L3 Cache (MB)	P- Core s	E- Core s	Total Cores	Processo r Threads	Memory Speed (MT/s) (DDR5)⁴	ECC Memory Supporte d⁵	Integrated Graphics	Featuring Intel® vPro® Technolog y ³	TDP (W)	Max Turbo Frequen Cy (GHz) ²
Intel 14 th Gene	eration Pro	ocessors													
Intel® Core™ i9-14900	2	1.50	5.4	4.3	36	8	16	24	32	5600	Y	Intel [®] UHD Graphics 770	Y	65	5.8
Intel® Core™ i7-14700	2.1	1.50	5.3	4.2	33	8	12	20	28	5600	Y	Intel [®] UHD Graphics 770	Y	65	5.4
Intel® Core™ i5-14600	2.7	2.00	5.2	3.9	24	6	8	14	20	5600	Y	Intel [®] UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-14500	2.6	1.80	5	3.7	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-14400	2.5	1.80	4.7	3.5	20	6	4	20	16	4800	N	Intel [®] UHD Graphics 730	N/A	65	4.7
Intel® Core™ i3-14100	3.5	N/A	4.7	N/A	12	4	0	4	8	4800	N	Intel [®] UHD Graphics 730	N	60	4.7
Intel 13 th Gene	eration Pro	ocessors													
Intel® Core™ i9-13900	2	1.50	5.2	4.2	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.6
Intel® Core™ i7-13700	2.1	1.50	5.1	4.10	30	8	8	16	24	5600	Y	Intel [®] UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-13600	2.7	2.00	5.0	3.7	24	6	8	14	20	4800	Y	Intel [®] UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-13500	2.5	1.80	4.8	3.5	24	6	8	14	20	4800	Y	Intel [®] UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-13400	2.5	1.80	4.6	3.3	20	6	4	10	16	4800	N	Intel [®] UHD Graphics 730	N/A	65	4.6
Intel® Core™- 13100	4.5	N/A	3.4	N/A	12	8	0	8	8	4800	N	Intel [®] UHD Graphics 730	N/A	60	4.5
Intel 12 th Gene	eration Pro	ocessors													
Intel® Core™ i7-12700	2.1	1.6	4.8	3.6	25	8	4	12	20	4800	Y	Intel [®] UHD Graphics 770	Y	65	4.9

Features

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

³ Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

⁴ Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro

⁵ Memory will run at 4400 speed (MT/s) in 2DPC within 1DIMM population; memory will run at 4000 speed (MT/s) in 2DPC within 2DIMM of 1 Rank population and memory will run at 3600 speed (MT/s) in 2DPC within 2DIMM of 2 Rank population



Features

GRAPHICS

Integrated Intel® Graphics

Intel® UHD Graphics 770 (integrated in 12th gen Corei5-12500T and above) Intel® UHD Graphics 730 (integrated in 12th gen Core i5-12400(T), and i3)

Optional Discrete Graphics Solutions

Intel Arc A380 6 GB FH 3DP+HDMI PCIe x16 Graphics Card

NVIDIA[®] GeForce[®] RTX 3070 8GB LHR Graphics Card¹

NVIDIA[®] GeForce[®] RTX 3060 12GB Graphics Card

NVIDIA® GeForce® RTX 3050 8 GB GDDR6 FH PCIe x16 Graphics Card

NVIDIA[®] T1000 8 GB GDDR6 Graphics Card

NVIDIA[®] T400 4GB Graphics Card

AMD Radeon RX 6300 2GB GDDR6 Graphics Card

Intel Arc A380 6GB Graphics Card

NVIDIA GeForce RTX 3050 8GB GDDR6 Graphics Card

NVIDIA T1000 8GB 4mDP Graphics Card

1. Requires 550W chassis

NOTE: HP Z1 G9 Tower Desktop PC can support a single discrete graphics card up to 200W with a 550W Power Supply.

Adapters and Cables

HP DisplayPort Cable

HP DisplayPort to HDMI True 4K Adapter

HP DisplayPort to VGA Adapter

HP USB to Serial Port Adapter

HP HDMI Standard Cable Kit (HDMI)



Features

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)

500GB 7200RPM 3.5in SATA HDD

1TB 7200RPM 3.5in SATA HDD

2TB 7200RPM 3.5in SATA HDD

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2.5 inch SATA Hard Disk Drives (HDD)**

500GB 7200RPM 2.5in SATA HDD

1TB 7200RPM 2.5in SATA HDD

2TB 5400RPM 2.5in SATA HDD

500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*

* Storage DriveLock does not work with Self Encrypting or Optane based storage.

** 2.5 inch SATA Hard Disk Drives are only available with the removable Hard Disk Drive carrier, and as the primary drive only. **NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

M.2 PCIe NMVe Solid State Drives (SSD)

256GB M.2 2280 PCIe NVMe SSD

512GB M.2 2280 PCIe NVMe SSD

1TB M.2 2280 PCIe NVMe SSD

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**

** Storage DriveLock does not work with Self Encrypting or Optane based storage **NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Optical Disc Drives

HP 9.5mm Slim DVD-ROM Drive¹

HP 9.5mm Slim DVD Writer Drive¹

 HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Media Card Reader

SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

MEMORY

Memory Type



Features

DDR5-4800 (Transfer rates up to 4400 MT/s), Max 128 GB, 4 U-DIMM

Memory Configuration

3 (1 x 8GB)
iB (2 x 8GB)
iB (4 x 8GB)
iB (1 x 16GB)
iB (2 x 16GB)
iB (4 x 16GB)
iB (1 x 32GB)
iB (2 x 32GB)
GB (4 x 32GB)
E: Memory modules support data transfer rates up to 3600 MT/s(2DPC/2R) or 4400 MT/s (2DPC/1R) and 4400 MT/s; actual data rate

NOTE: Memory modules support data transfer rates up to 3600 MT/s(2DPC/2R) or 4400 MT/s (2DPC/1R) and 4400 MT/s; actual data rate is determined by the system configured.

NOTE: 2 DIMMs per channel requires platform design with four physical DIMM slots. 2 DIMMS per channel is supported when channel is populated with the same DIMM part number. Symmetric configurations are required for 2 DIMMs per channel physical configuration. Population rule: ensure furthest DIMM from processor is populated. **NOTE:** All memory slots are customer accessible / upgradeable.

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)

Intel[®] I219-LM 1 Gigabit Network Connection LOM (vPro[®])

Intel[®] Ethernet Network Adapter I225-T1 (optional)

Wireless

Intel[®] Wi-Fi 7³ +Bluetooth 5.4 non-vPro WW WLAN

Intel® Wi-Fi 6E¹ AX211 + BT5.3 wireless card (802.11AX 2x2 vPro®, supporting gigabit data rate²)

Intel[®] Wi-Fi 6E¹ AX211 + BT5.3 wireless card (802.11AX 2x2 non-vPro[®], supporting gigabit data rate²)

Realtek RTL8852BE 802.11ax³ 2x2 Wi-Fi[®] 6² + BT5.3 wireless card

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

2. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

3. not available with ADL processors; Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires Windows 11 24H2, select Intel® processor, and a Wi-Fi 7 router, sold separately. Wi-Fi 7 is backwards compatible with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported. NOTE: Intel Wi-Fi 6E modules are available, but the 6GHz band is not available.



Features

KEYBOARDS AND POINTING DEVICES

Keyboards

HP Wired Desktop 320K Keyboard

HP USB Business Slim Wired SmartCard CCID Keyboard

HP Business Slim PS/2 Wired Keyboard

HP 125 Wired Keyboard

HP 125 AntiMicrobial Wired Keyboard (China Only)

Mouse

HP Wired 320M Mouse

HP PS/2 Mouse

HP Wired 125 Mouse

HP Wired 128 Laser Mouse

HP Wired 125 Antimicrobial Mouse (China only)

Keyboard and Mouse Combo

HP 655 Wireless Keyboard and mouse combo



Features

SECURITY

TPM 2.0 endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.
Solenoid Lock & Intrusion Sensor (optional)
Support for chassis cable lock devices
Support for chassis padlocks devices
SATA port disablement (via BIOS)
Serial, USB enable / disable (via BIOS)
Serial, parallel, USB enable / disable (via BIOS)
Optional USB Port Disable at factory (user configurable via BIOS)
Removable media write/boot control
Power-on password (via BIOS)
Setup password (via BIOS)

PORTS

I/O Ports – Internal Ports

PCI Express 4.0 x16	1			
PCI Express 3.0 x16 (wired as x4)	1			
PCI Express 3.0 x1	2			
SATA port	4			
M.2 PCIe (1) M.2 PCIe 3 x1 2230 (for WLAN) (2) M.2 PCIe 4 x4 2280 (for storage)				
1. M.2 SSD attached to CPU is PCIe Gen 4, the other two M.2 are PCIe Gen 3 (AIO)				

NOTE: For Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after-market option).

Standard User Accessible Ports

Type-A Hi-Speed USB 480Mbps signaling rate port	3(rear)		
Type-A SuperSpeed USB 5 Gbps signaling rate port	3 (rear)		
Type-A SuperSpeed USB 10 Gbps signaling rate port	4 (front)		
Type-C [®] SuperSpeed USB 20Gbps signaling rate port	1 (front)		
Video	2 DisplayPort™ 1.4a 1 HDMI 1.4		
Audio	1 Universal Audio Jack with CTIA and OMPT headset support (front); 1 Audio-Line-in/Line out (rear)		

(1) Flexible Port 1, choice of <u>one</u> of the following...

Dual Type-A SuperSpeed USB 5 Gbps signaling rate port	1
Type-C [®] SuperSpeed USB 10Gbps signaling rate port	1



Features

1 DisplayPort™ 1.4a <u>or</u>
HDMI 2.0b <u>or</u> VGA
1

Bays

(2) Slim Optical Disc Drive (ODD or removable storage)
(1) SD Card Reader
(2) 3.5" Internal Storage Drive
4. SATA 2.5" internal storage drive cannot be selected if discrete graphic card is selected.



Features

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2

Features

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Easy Clean²⁰ HP PC Hardware Diagnostics UEFI HP Desktop Support Utilities HP Privacy Settings HP Setup Integrated OOBE HP Support Assistant² HSA Fusion for Commercial HSA Telemetry for Commercial Touchpoint Customizer for Commercial myHP HP Notifications HP Connection Optimizer HP Smart Support³ Buy Microsoft Office (sold separately)

Manageability Features

HP Connect for Microsoft Endpoint Manager⁴ HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download)⁵ HP Client Management Script Library (download) HP Patch Assistant (download)⁶ HP Driver Packs (download)¹⁹ HP Cloud Recovery⁷ HP Client Catalog (download)

Security Management

HP Wolf Security for Business⁸ includes: HP Sure Click⁹ HP Sure Sense 2¹⁰ HP Sure Run Gen5¹¹ HP Sure Recover Gen5¹² HP Sure Start Gen7¹³ HP Tamper Lock HP Sure Admin¹⁴ HP Client Security Manager Gen7¹⁵

BIOS

HP BIOSphere Gen6¹⁶ HP Secure Erase¹⁷ HP DriveLock & Automatic DriveLock BIOS Update via Network Absolute Persistence Module¹⁸ TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

2. HP Support Assistant requires Windows and Internet Access

3. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
4. HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.

5. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

6. HP Patch Assistant available on select HP PCs with the HP Manageability Kit that are managed through Microsoft System Center Configuration Manager. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.



HP Z1 G9 Tower Desktop PC

QuickSpecs

Features

7. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. **NOTE:** You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail, please refer to: https://support.hp.com/us-en/document/c05115630.

8. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.

9. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

10. HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome[™], and Chromium[™]. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

11. HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.

12. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

13. HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.

14. HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

15. HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.

16. HP BIOSphere Gen6 features may vary depending on the platform and configuration.

17. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

18. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.

19. HP Driver Packs: Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement .

20. HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.



Features

ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

ENERGY STAR[®] certified. EPEAT[®] registered where applicable. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] Gold with Climate+ registered. See <u>www.epeat.net</u> for registration status and tier levels by country Low halogen (chassis, all internal components and modules)¹ TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
 is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C)¹ Non-operating: -22° to 149° F (-30° to 65° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)
1. On constitution to service the service of the se	wated 1.0 days C and 200 m (1000 ft) to 2000 m (10,000 ft) shows and lowel

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Features

HP Z1 G9 Tower Desktop PC

Frond John Contifications		he process of house sertified to the	following approvals and mark				
Eco-Label Certifications &	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:						
declarations	• IT ECO declaration						
		• US ENERGY STAR®					
	• ENERGY STAR [®] certified. EPEAT [®] registered where applicable. Based on US EPEAT [®] reg according to IEEE 1680.1-2018 EPEAT [®] . EPEAT [®] status varies by country. Visit						
	http://www.epeat.net for more information.						
	http://www.cpcdt.net for more information.						
Sustainable Impact	45% post-consumer recy	cled plastic					
Specifications	 45% post-consumer recycled plastic 5% ITE-derived closed loop plastic 						
Specifications		op plastic					
	Bulk packaging available						
	80 Plus [®] Platinum power						
	 Molded paper pulp cushic 	on inside box is 100% sustainably s	ourced and recyclable				
	 Ocean-bound plastic in sp 	beaker enclosure and system fan					
	Contains recycled metal						
System Configuration	The configuration used for the Ene	ergy Consumption and Declared No	ise Emissions data for the				
	Desktop model is based on a Typic						
Energy Consumption							
(in accordance with US	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz				
ENERGY STAR [®] test							
method)	27.15.14	27.45.14					
Normal Operation (Short idle)	27.15 W	27.45 W	27.2 W				
Normal Operation	26.07 W	25.96 W	25.45 W				
(Long idle)	20.07 W	25.50 W	25.75 W				
Sleep	1.36 W	1.34 W	1.32 W				
Off	0.76 W	0.72 W	0.71 W				
	family. HP computers marked with the Environmental Protection Agency (EP) not offer ENERGY STAR® compliant co	for an ENERGY STAR® compliant produ e ENERGY STAR® Logo are compliant wi A) ENERGY STAR® specifications for cor nfigurations, then energy efficiency da ive, a high efficiency power supply, and	ith the applicable U.S. mputers. If a model family does Ita listed is for a typically				
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz				
Normal Operation (Short	92.9 BTU/hr	93.9 BTU/hr	93 BTU/hr				
idle)							
Normal Operation (Long idle)	89.2 BTU/hr	88.8 BTU/hr	87 BTU/hr				
Sleep							
Off	4.7 BTU/hr	4.6 BTU/hr	4.5 BTU/hr				
UII	4.7 BTU/hr 2.6 BTU/hr	4.6 BTU/hr 2.5 BTU/hr	4.5 BTU/hr 2.4 BTU/hr				
	2.6 BTU/hr		2.4 BTU/hr				
Longevity and Upgrading	2.6 BTU/hr NOTE: Heat dissipation is calculated b one hour.	2.5 BTU/hr ased on the measured watts, assuming ssibly extending its useful life by se	2.4 BTU/hr g the service level is attained for				
	2.6 BTU/hr NOTE: Heat dissipation is calculated b one hour. This product can be upgraded, pos features and/or components conta Spare parts are available through	2.5 BTU/hr ased on the measured watts, assuming ssibly extending its useful life by se	2.4 BTU/hr g the service level is attained for everal years. Upgradeable				
	2.6 BTU/hr NOTE: Heat dissipation is calculated b one hour. This product can be upgraded, postfeatures and/or components contained.	2.5 BTU/hr ased on the measured watts, assuming ssibly extending its useful life by se ained in the product may include: out the warranty period and or for u	2.4 BTU/hr g the service level is attained for everal years. Upgradeable				



Not all configuration components are available in all regions/countries. c08112669– DA 17011– Worldwide – Version 18 – March 18, 2024

Features

	1			
	Mercury greater the 1 ppm by weight			
	Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -			
	2011/65/EC	•		
			rical and Electronic Equipment (WEEE)	
	 This HP product is designed to comply with the Waste Electrical and Electronic Equipment (V Directive – 2002/96/EC. 			
		ct is in compliance with California Proposition 65	(State of California; Safe Drinking	
	 Water and Toxic Enforcement Act of 1986). • ENERGY STAR[®] certified. EPEAT[®] 2019 registered where applicable. Based on US EPEAT[®] 			
		according to IEEE 1680.1-2018 EPEAT®. Status va	aries by country. Visit	
		epeat.net for more information.		
		rts weighing over 25 grams used in the product a		
		ct contains a minimum of 35% post-consumer re	cycled plastic (by wt.); including 10%	
		post-consumer recycled plastic*		
	• This produ	ct is 93.5% recycle-able when properly disposed	of at end of life.	
	*NOTE: Recvo	led plastic content percentage is based on the definitio	on set in the IEEE 1680.1-2018 standard.	
N . 1	-			
Packaging Materials	External:	PAPER/Corrugated	1106 g	
	1	PAPER/Molded Pulp	666 g	
Mata: 21 Mar as	Internal:	PLASTIC/Polyethylene low density - LDPE	40 g	
Material Usage		t does not contain any of the following substances	s in excess of regulatory limits (refer	
		to the HP General Specification for the Environment at		
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):			
	Asbestos Colorante			
	 Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds 			
	Mercuric Oxide Batteries			
	 Nickel – finishes must not be used on the external surface designed to be frequently handle carried by the user. Ozone Depleting Substances 			
 Polybrominated Biphenyls (PBBs) 				
	Polybrominated Biphenyl Ethers (PBBEs)			
	Polybrominated Biphenyl Oxides (PBBOs)			
	Polychlorinated Biphenyl (PCB)			
	Polychlorinated Terphenyls (PCT)			
	Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been			
	voluntarily removed from most applications.			
	Radioactive Substances Tributul Tin (TDT) Tributul Tin Ouida (TDTO)			
		n (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TB		
Packaging Usage		hese guidelines to decrease the environmental in		
	• Eliminate t	he use of heavy metals such as lead, chromium, r	mercury and cadmium in packaging	
	materials.			
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.			
			-	
	Design page	kaging materials for ease of disassembly.		



Features

	 Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials.
	• Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
Footnotes	¹ ITE Derived Closed Loop Plastic percentage is based on the definition set in the IEEE 1680.1-2018
	standard.
	² Percentage of ocean-bound plastic contained in each component varies by product
	⁴ Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018
	standard.
	⁵ Molded pulp cushions are made from 100% recycled wood fiber and organic materials.



Features

SERVICE AND SUPPORT

On-site Warranty¹: One-year (1-1-1) limited warranty delivers one years of on-site, next business day² service for parts and labor and includes free support 24 x 7³. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.⁴

1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
 Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x

7 support may not be available in some countries.

4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Certification and Compliance

Environmental Sustainability questions concerning:

- This product is low halogen except for power cords, cables, and peripherals. Service parts obtained after purchase may not be Low Halogen.
- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

•

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpukmu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics
- •

Please contact techregshelp@hp.com

Energy Efficiency Compliance

ENERGY STAR[®] certified. EPEAT[®] registered where applicable. EPEAT [®] registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.



Technical Specifications – Processors

PROCESSORS

12th and 13th Generation Intel[®] Core™ Processors

All HP Z1 G9 Tower PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP Z1 series G9 Desktop Business PC.

Intel[®] Management Engine (ME) v16 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16 includes the following advanced management functions:

- Support for configuration of Intel ME 16.0 capabilities
- No reset after provisioning
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
 - Public Key Infrastructure
- Profile Editor and Profile Editor Plugin Interface
- Required Permissions for Solutions Framework

Technical Specifications – Graphics

GRAPHICS

Intel [®] UHD Graphics (integrated)	
VGA Controller	Integrated
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), Onboard support HBR2 link rates/option DP support to HBR3 and Multi-Stream Technology for a maximum of 4 displays connected to any output controlled by Intel® Graphics
HDMI (onboard / optional)	Supports HDMI 2.0b features (onboard HDMI support HDMI1.4; Option HDMI support HDMI2.0b) Supports HDCP 2.3 (Support HDCP 1.4/2.3) Supports audio over HDMI
VGA (optional)	VGA output
USB-C® DP Alt Mode (optional) Memory	DisplayPort [™] over the optional USB-C [®] module (Support DP1.4 HBR2) The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 16 bits/color
Graphics/Video API Support	HEVC 10b Enc/12b Dec HW
	VP9 12b Dec HW à AV1 decode support 8/10b, 4:2:0 HDR
	Rec. 2020 DX12
Max. Resolution (VGA Option)	2048 x 1536@60Hz
Max. Resolution (Onboard HDMI)	1920 x 1080@60Hz
Max. Resolution (Option HDMI)	3840 x 2160@60Hz
Max. Resolution (On board DP)	3840 x 2160@60Hz
Max. Resolution (Option DP)	5120 x 2280@60Hz

NVIDIA® GeForce® RTX 3050 8GB GDDR6 Graphics Card

Engine Clock	Base: 1515 Mhz Boost: 1755 Mhz
Frame Buffer Size / Width	8GB/128bit
Graphic Memory Type / Clock	512Mx32 GDDR6 @ 4 pcs/14Gbps
Max. Resolution (HDMI)	7680x4320@60Hz
Max. Resolution (DP)	7680x4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	HDMIx1+ DPx3
Cooling (active/passive)	Active fansink with 4 pin fan control
Total power consumption (W)	120W
Form-factor	ATX (X:144.7mm/Y:111.15mm/Z: 36.70mm) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 3060 LHR Graphics Card

Engine Clock	1320 MHz
Memory Clock	1875 MHz
Memory Size(width)	12 GB (256-bit)
Memory Type	256M x 32 GDDR6



Technical Specifications – Graphics

Max. Resolution (HDMI)	7680x4320@60Hz
Max. Resolution (DP)	7680x4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	HDMIx1+ DPx3
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	170W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 3070 LHR Graphics Card

Engine Clock	1730 MHz
Memory Clock	8000 MHz
Memory Size(width)	8 GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution (HDMI)	7680x4320@60Hz
Max. Resolution (DP)	7680x4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	HDMIx1+ DPx3
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	<220W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® T400 2GB Graphics Card

Engine Clock	2100 MHz
Memory Clock	5001 MHz
Memory Size (width)	2GB (64-bit)
Memory Type	256M x 16 GDDR6
Max. Resolution (DP)	7680x4320@120Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	mDPx3
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	30W

NVIDIA® T400 4GB Graphics Card

Engine Clock	2100 MHz
Memory Clock	5001 MHz
Memory Size (width)	4GB (64-bit)
Memory Type	512M x 16 GDDR6
Max. Resolution (DP)	7680x4320@120Hz
Multi Display Support	4 displays
HDCP Compliance	Yes



Technical Specifications – Graphics

Rear I/O connectors (bracket)	mDPx3
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	30W
PCB form-factor with bracket	LP PCB with LP bracket

NVIDIA® T1000 8GB GDDR6 Graphics card

Engine Clock	Base: 1065 Mhz Boost: 1395 Mhz
Frame Buffer Size / Width	8GB/128bit
Graphic Memory Type / Clock	4 pcs 2Ch x 256M x 16 GDDR6/Max 5001 Mhz
Max. Resolution (DP)	7680x4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	mDPx4
Cooling (active/passive)	Active
Total power consumption (W)	50W
Form-factor	X: 155.88mm/Y: 68.91mm, single slot

Intel® Arc™ A380 6GB GDDR6 Graphics card

Engine Clock	2150Mhz
Frame Buffer Size / Width	6GB/96bit
Graphic Memory Type / Clock	GDDR6 ,3 pcs/15.5Gbps
Max. Resolution (HDMI)	4096 x2160@60Hz
Max. Resolution (DP)	7680x4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	DP x3 + HDMI x1
Cooling (active/passive)	Active
Total power consumption (W)	75W

Technical Specifications – Storage

FOR CR 7200PDM 2 Fin SATA HDD

300 GB / 200KPM 3.3III SATA HDD	
Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	64 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width (nominal)	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	3,907,050,336
Seek Time	11 ms (Average)
Height	1.028 in/26.11 mm
Width (nominal)	Media diameter: 3.5 in/88.9 mm Physical size: 4 in/102 mm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



500 GB 7200RPM 2.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.283 in/7.2 mm (Max.)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1 TB 7200RPM 2.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.283 in/7.2 mm (Max.)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2 TB 5400RPM 2.5in SATA HDD

Capacity	2 TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	3,907,050,336
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity	500 GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.283 in/7.2 mm (Max.)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256 GB M.2 2280 PCIe NVMe SSD		
Drive Weight	< 10g	
Capacity	256 GB	
Height	2.3 mm	
Length	80 mm	
Width	22 mm	
Interface	PCIe NVMe	
Maximum Sequential Read	2000 MB/s +/- 20%	
Maximum Sequential Write	900 MB/s +/- 20%	
Logical Blocks	500,118,192	
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]	
Features	TRIM; L1.2	

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.3 mm
Length	80 mm
Width	22 mm
Interface	PCIe NVMe
Maximum Sequential Read	2000 MB/s +/- 20%
Maximum Sequential Write	1000 MB/s +/- 20%
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1 TB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.3 mm
Length	80 mm
Width	22 mm
Interface	PCIe NVMe
Maximum Sequential Read	2200 MB/s +/- 20%
Maximum Sequential Write	1200 MB/s +/- 20%
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Value SSD

Capacity	256 GB
Interface	PCIE NVMe
Maximum Sequential Read	2000 MB/s ±20%
Maximum Sequential Write	900 MB/s ±20%
Logical Blocks	500,118,192
Features	Pyrite 2.0; TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.3 mm
Length	80 mm



Technical Specifications – Storage

Width	22 mm
Interface	PCIE Gen4x4
Maximum Sequential Read	4000 MB/s ±20%
Maximum Sequential Write	2000 MB/s ±20%
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

-
< 10g
512 GB
2.3 mm
80 mm
22 mm
PCIE Gen4x4
6400 MB/s ±20%
3500 MB/s ±20%
1,000,215,216
0° to 70°C (32° to 158°F) [ambient temp]
TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.3 mm
Length	80 mm
Width	22 mm
Interface	PCIE Gen4x4
Maximum Sequential Read	6400 MB/s ±20%
Maximum Sequential Write	5000 MB/s ±20%
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	2 TB
Height	2.3 mm



Length	80 mm
Width	22 mm
Interface	PCIE Gen4x4
Maximum Sequential Read	6400 MB/s ±20%
Maximum Sequential Write	5000 MB/s ±20%
Logical Blocks	4,000,797,360
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.3 mm
Length	80 mm
Width	22 mm
Interface	PCIE Gen4x4
Maximum Sequential Read	4000 MB/s ±20%
Maximum Sequential Write	2000 MB/s ±20%
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.3 mm
Length	80 mm
Width	22 mm
Interface	PCIE Gen4x4
Maximum Sequential Read	6400 MB/s ±20%
Maximum Sequential Write	3500 MB/s ±20%
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

OPTICAL DISC DRIVES

HP 9.5mm Slim DVD-ROM Drive



Technical Specifications – Storage

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	Up to 0.31 lb (140g) without bezel
Read Speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X
Access time (typical reads, including settling)	Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

IIF 5.5IIIIII SUIII DVD WIILEI L	
Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)
Write Speeds	DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 6X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+RW - Up to 8X
Read Speeds	DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications – Storage



Technical Specifications – Networking and Communications

NETWORKING AND COMMUNICATIONS

Intel® I219-LM 1 Gigabit	Network Connection LOM (vPro®)
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling (Hash Mode Only)
	Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame);
	Wake-on-LAN from off (Magic Packet only)
	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel [®] vPro [®] support with appropriate Intel [®] chipset components

Intel® I225-LM 2.5 Giga	bit Network Connection LOM (non-vPro®)
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)
	4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126)
	5. Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31–32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
	IEEE 802.3i 10BASE-T
	IEEE 802.3u 100BASE-TX
	IEEE 802.3ab 1000BAE-T
	IEEE 802.3bz 2.5GBASE-T



Technical Specifications – Networking and Communications

Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling (Hash Mode Only)
	Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame);
	Wake-on-LAN from off (Magic Packet only)
	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel [®] non-vPro [®] support with appropriate Intel [®] chipset components

Realtek RTL8852BE 802.11ax 2x2 Wi-Fi + BT5.3 (802.11ax 2x2, supporting gigabit data rate) ¹		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
	IEEE 802.11ax	
	IEEE 802.11d	
	IEEE 802.11e	
	IEEE 802.11h	
	IEEE 802.11i	
	IEEE 802.11k	
	IEEE 802.11r	
	IEEE 802.11v	
Interoperability	Wi-Fi certified modules	
Frequency Band	802.11b/g/n/ax	
	• 2.402 – 2.482 GHz	
	802.11a/n/ac/ax	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: max 300Mbps	
	• 802.11ac: max 866.7Mbps	
	• 802.11ax: max 1201Mbps	
Modulation	Direct Sequence Spread Spectrum	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM	
Security ²	 IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only 	
	AES-CCMP: 128 bit in hardware	



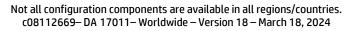
Technical Specifications – Networking and Communications

	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b : +18.5dBm minimum
output i owei	• 802.11g : +17.5dBm minimum
	• 802.11a : +18.5dBm minimum
	• 802.11n HT20(2.4GHz) : +15.5dBm minimum
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum
	• 802.11n HT20(5GHz) : +15.5dBm minimum
	• 802.11n HT40(5GHz) : +14.5dBm minimum
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum
	• 802.11ax HE40(2.4GHz) : +10dBm minimum
	802.11ax HE80(5GHz): +10dBm minimum
Power Consumption	Transmit mode :2.5 W
	• Receive mode :2 W
	Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode :50 mW (WLAN unassociated)
	 Connected Standby/Modern Standby: 10mW
	• Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
_	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps : -84dBm maximum
	802.11a/g, 6Mbps : -86dBm maximum
	802.11a/g, 54Mbps : -72dBm maximum
	802.11n, MCS07 : -67dBm maximum
	802.11n, MCS15 : -64dBm maximum
	802.11ac, MCS0 : -84dBm maximum
	802.11ac, MCS9 : -59dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
weight	
Operating Voltage	2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)



Technical Specifications – Networking and Communications

LED Activity	LED Ambor - Padio OEE:
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blu	etooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Technology
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or
	864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
	transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	Selective Suspend: 17 mW
Electrical Interface	Microsoft Windows Bluetooth Software
Bluetooth [®] Software Supported Link Topology	Microsoft Windows ACPI, and USB Bus Support
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	Selective Suspend: 17 mW
Power Management	Microsoft Windows Bluetooth Software
Certifications	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 – Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
	BT5.1



ESR9/10 Compliance
LE Advertisement Extensions
Channel Selection Algo
Limited High Duty Cycle Non-Connectable Advertising
2Mbps LE
LE Long Range

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel AX211 Wi-Fi 6E +BT 5.3 M.2 160MHz CNVi WW WLAN ¹		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
	IEEE 802.11ax	
	IEEE 802.11d	
	IEEE 802.11e	
	IEEE 802.11h	
	IEEE 802.11i	
	IEEE 802.11k	
	IEEE 802.11r	
	IEEE 802.11v	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n/ax	
	• 2.402 – 2.482 GHz	
	802.11a/n/ac/ax	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
	• 5.955 – 6.415 GHz	
	• 6.435 – 6.515 GHz	
	• 6.535 – 6.875 GHz	
	• 6.895 – 7.115 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: max 300Mbps	
	• 802.11ac: 1733Mbps	
	• 802.11ax : max 2.4Gbps	
Modulation	Direct Sequence Spread Spectrum	
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
	, 1024QAM	
Security ²	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
	• AES-CCMP: 128 bit in hardware	
	802.1x authentication	



	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification 	
	WPA3 certification	
	• IEEE 802.11i	
	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models		
	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ³	• 802.11b: +17dBm minimum	
	• 802.11g: +16dBm minimum	
	• 802.11a: +17dBm minimum	
	• 802.11n HT20(2.4GHz) : +14dBm minimum	
	• 802.11n HT40(2.4GHz) : +13dBm minimum	
	• 802.11n HT20(5GHz) : +14dBm minimum	
	• 802.11n HT40(5GHz) : +13dBm minimum	
	• 802.11ac VHT80(5GHz) : +10dBm minimum	
	• 802.11ac VHT160(5GHz) : +10dBm minimum	
	• 802.11ax HE40(2.4GHz) : +12dBm minimum	
	• 802.11ax HE80(5GHz) : +10dBm minimum	
	• 802.11ax HE160(5GHz) : +10dBm minimum	
Power Consumption	• Transmit mode 2.0 W	
	• Receive mode 1.6 W	
	Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode 50 mW (WLAN unassociated)	
	a Connected Standby 10mW	
	Connected Standby 10mW	
	• Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management	
Power Management		
D	802.11 compliant power saving mode	
Receiver Sensitivity ⁴	•802.11b, 1Mbps : -93.5dBm maximum	
	•802.11b, 11Mbps : -84dBm maximum	
	• 802.11a/g, 6Mbps : -86dBm maximum	
	• 802.11a/g, 54Mbps : -72dBm maximum	
	• 802.11n, MCS07 : -67dBm maximum	
	• 802.11n, MCS15: -64dBm maximum	
	• 802.11ac, MCSO(VHT80) : -84dBm maximum	
	• 802.11ac, MCS9(VHT80) : -59dBm maximum	
	• 802.11ac, MCS9(VHT160) : -58.5dBm maximum	
	•802.11ax, MCS11(HE40): -57dBm maximum	
	•802.11ax, MCS11(HE80): -54dBm maximum	
	•802.11ax, MCS11(HE160): -53.5dBm maximum	
Antenna type	•802.11ax, MCS11(HE160): -53.5dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure	
Antenna type		
Antenna type		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications PCI-Express M.2 MiniCard	
	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications PCI-Express M.2 MiniCard 1. Type 2230: 2.3 x 22.0 x 30.0 mm	
Form Factor	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications PCI-Express M.2 MiniCard	



Operating Voltage	3.3v +/- 9%	
Temperature	Operating: 14° to 158° F (–10° to 70° C)	
-	Non-operating: –40° to 176° F (–40° to 80° C)	
Humidity	Operating: 10% to 90% (non-condensing)	
	Non-operating: 5% to 95% (non-condensing)	
Altitude	Operating: 0 to 10,000 ft (3,048 m)	
	Non-operating: 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON	
HP Integrated Module with Blue	etooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Technology	
Frequency Band 2402 to 2480 MHz		
Number of Available Channels Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.	
Power Consumption	Peak (Tx): 330 mW	
	Peak (Rx): 230 mW	
	Selective Suspend: 17 mW	
Bluetooth° Software Supported Link Topology	Microsoft Windows Bluetooth Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826	
Certifications Power Management Certifications		
Power Management	ETS 300 328, ETS 300 826	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Power Management	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX)	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP)	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HFP)	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Link Layer Privacy LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HFP)	



	Channel Selection Algo
	Limited High Duty Cycle Non-Connectable Advertising
	2Mbps LE
	LE Long Range
1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless	

router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel AX211 Wi-Fi 6E +BT 5.3 M.2 vPro® 160MHz CNVi WW WLAN ¹		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
	IEEE 802.11ax	
	IEEE 802.11d	
	IEEE 802.11e	
	IEEE 802.11h	
	IEEE 802.11i	
	IEEE 802.11k	
	IEEE 802.11r	
	IEEE 802.11v	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n/ax	
Frequency bana	• 2.402 – 2.482 GHz	
	802.11a/n/ac/ax	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
	• 5.955 – 6.415 GHz	
	• 6.435 – 6.515 GHz	
	• 6.535 – 6.875 GHz	
Data Rates	• 6.895 – 7.115 GHz • 802.11b: 1, 2, 5.5, 11 Mbps	
Dala Rales		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: max 300Mbps	
	• 802.11ac: 1733Mbps	
Modulation	802.11ax: max 2.4Gbps	
Modulation	Direct Sequence Spread Spectrum	
	OFDM DEEK OEK CCK 16 OAM CA OAM DEC OAM	
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Committee?	, 1024QAM	
Security ²	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification WPA3 certification	
	• IEEE 802.11i	
Notice of Aughite struct	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infractructure (Access Daint Dequired)	
Boaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points	
Roaming Output Power ³		
output Power ²	• 802.11b : +17dBm minimum	
	• 802.11g : +16dBm minimum	
	• 802.11a : +17dBm minimum	
	• 802.11n HT20(2.4GHz) : +14dBm minimum	
	• 802.11n HT40(2.4GHz) : +13dBm minimum	
	• 802.11n HT20(5GHz) : +14dBm minimum	



	• 802.11n HT40(5GHz) : +13dBm minimum
	• 802.11ac VHT80(5GHz) : +10dBm minimum
	• 802.11ac VHT160(5GHz) : +10dBm minimum
	• 802.11ax HE40(2.4GHz) : +12dBm minimum
	• 802.11ax HE80(5GHz) : +10dBm minimum
	• 802.11ax HE160(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
	a Despise mode 1 C W
	• Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	 Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	•802.11b, 1Mbps : -93.5dBm maximum
	•802.11b, 11Mbps : -84dBm maximum
	• 802.11a/g, 6Mbps : -86dBm maximum
	• 802.11a/g, 54Mbps : -72dBm maximum
	• 802.11n, MCS07 : -67dBm maximum
	• 802.11n, MCS15 : -64dBm maximum
	• 802.11ac, MCS0(VHT80) : -84dBm maximum
	• 802.11ac, MCS9(VHT80) : -59dBm maximum
	• 802.11ac, MCS9(VHT160) : -58.5dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
	•802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	righternelency unterna with spatial aversity, mounced in the display chelosare
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
-	2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blu	letooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Technology
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
5.	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps



	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.	
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW	
	Peak (Rx): 230 mW Selective Suspend: 17 mW	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826	
	Low Voltage Directive IEC950	
	UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance	
	LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range	

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. 2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



I/O DEVICES

HP Business Slim Standal	one USB/PS2 Wired Keyboard	
Physical Characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)
	Weight	1.32 lb (0.6± 0.08 kg)
Electrical	Operating voltage	4.4-5.25VDC
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)/
	System interface	USB or PS/2
	ESD	Contact Discharge: 2, 4,6,8KV Air Discharge: 2, 4, 8,10,12.5KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Кеусарѕ	Low-profile design
	Switch actuation	60±12.5g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	Minus 30 degrees to 60 degrees Celsius
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI	, BSMI, RCM, KCC
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and	I TUVGS

HP USB Business Slim Wired SmartCard CCID Keyboard		
Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)



	Dimensions (L x W x H)	17.34 x 5.68 x 0.78in (440.6 x 144.5 x 1.98 cm)
	Weight	1.32 lb (598g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	100mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	CE Marking, TUV, EAC, FCC, cUL	us/CSAus, ICES, RCM, VCCI, KCC, BSMI
Ergonomic compliance	ISO 9241-4, TUVGS	

HP 125 (AntiMicrobial) Wired Keyboard (China only)

Physical Characteristics	Keys	104/105/107/109layout (depending upon country)
	Dimensions (L x W x H)	436 x 138 x24.7 mm
	Weight	471g
Electrical	Operating voltage	5V +- 5%
	Power consumption	50mA
	System interface	USB Type A plug connector



QuickSpecs

	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	55±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	1.8 m
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-4° to 149° F (-20° to 65° C)
	Operating humidity	10% to 95% (non-condensing at ambient)
	Non-operating humidity	0% to 95% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI,	BSMI, RCM, KCC, USB-IF, WHQL, EN/IEC 60601-1
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and	I TUVGS

HP 655 wireless Keyboard			
Physical Characteristics	Keys	104, 105, 107,109 layouts	
	Dimensions (L x W x H)	16.86 x 4.55 x 0.71 in (428.22 x 115.47 x 18.06 mm)	
	Weight	0.96 lb (435g)	
Electrical	Operating voltage	3 VDC, +/-5%	
	Power consumption	20 mA Max (All LED on)	
	System interface	2.4GHz Wireless	
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Mechanical	Кеусарѕ	Plunger, 2.0 mm key travel	
	Key actuation	60±10g nominal peak force with tactile feedback	
	Key life	10 million keystrokes (Life tester)	
	Key structure type	Rubber dome & Membrane	



	Key-leveling mechanisms	For all double-wide and greater-length keys	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals		C, I TRC, TRA, CASA, UA, EAC, CNC, ANATEL, NOM-NYCE BIS, PosTel, VCCI, TELEC, KC, MCMC, IDA, BSMI, NCC,	
Ergonomic compliance	TUVGS	TUVGS	

IP Wired Desktop 320K Keyboard			
	Keys	104, 105, 107,109 layouts	
Physical Characteristics	Dimensions (L x W x H)	18.86*4.55*0.66 in (426.2 x 110.9 x 16.7 mm)	
	Weight	1.00 lb(452g)	
	Operating voltage	5 VDC, +/-5%	
	Power consumption	50 mA Max (All LED on)	
Electrical	System interface	USB Port	
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)	
	EMI - RFI	European Standard EN 55022: 2006+A1: 2007, Class B. FCC/CFR 47: Part 15 Class B	
Mechanical	hanical Keycaps 2.0mm +/-0.2mm at 120gf Key travel		
	Operating temperature	10° C to 90° C	
	Non-operating temperature	-30° C to 95° C	
Environmental	Operating humidity	N/A	
	Non-operating humidity	10% to 90% (non-condensing at ambient)	
	Operating shock	N/A	



	Non-operating shock	 i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired. ii. Trapezoidal Shock- Transportation Environment, Non-Operational Sample size: 5pcs. Condition: Sample power off. Orientation: All six faces: Front, Rear, Left, Right, Bottom, and Top. Configuration: As intended for shipment Number of shocks: 1 shock/face. Minimum faired acceleration: 30G's. Test also at 40 and 50G's to find margin. Velocity change: 266lps (inch-per-second) for product mass (m) 20<m<40lbs.< li=""> </m<40lbs.<>		e of operation. 5 desired. , Non-Operational ottom, and Top. 9 and 50G's to find	
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
	Operating vibration	5-350	0	0.0001	
		350-500	-6	-	
		500	-	0.00005	
		(~0.21Gnms)			
		Total Test time: 10 minutes			
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
		5.100	0	0.015	
	Non-operating vibration	100-137	-6	-	
		137-350	0	0.008	
		252 502	C		
		350-500	-6	-	
		<u> </u>	-b -	- 0.0039	
	Drop (out of box)		-	0.0039	
	Drop (out of box) Drop (in box)	500 76cm on carpet, six-drop	-		
Approvals		500 76cm on carpet, six-drop 10 times drop including 6 Drop Height: 91cm	- sequence faces, one corner and 3 e		

HP Wired Desktop 320M Mouse		
	Keys	Left/right key
Physical Characteristics	Dimensions (L x W x H)	4.09 x2.50 x 1.40 in (103.8x 63.4 x 35.5 mm)
	Weight	0.16 lb(72g)
Electrical	Operating voltage	5 VDC, +/-0.25V
	Power consumption	100 mA Max
	System interface	USB Port
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)
		European Standard EN 55022: 2006+A1: 2007, Class B. FCC/CFR 47: Part 15 Class B



Approvals Ergonomic compliance	CB, CE, FCC, cULus, ICES, EAC, TUVGS	, NOM-NYCE SCT, RCM, VCC	CI, KC, BSMI		
_					
	Drop (in box)	N/A			
	Drop (out of box)	76cm on carpet, six-drop	sequence		
		500	-	0.0039	
		350-500	-6	-	
		137-350	0	0.008	
	Non-operating vibration	100-137	-6		
		5.100	0	0.015	
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
		Total Test time: 10 minutes			
		500	- (~0.21Gnms)	0.00005	
	Operating vibration	350-500	-6	-	
		5-350	0	0.0001	
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
Environmental		Configuration: As intende Number of shocks: 1 shoo Minimum faired accelerat margin. Velocity change: 266lps (20 <m<40lbs.< th=""><th>Front, Rear, Left, Right, B ed for shipment ck/face. ion: 30G's. Test also at 40 inch-per-second) for prod</th><th>) and 50G's to find luct mass (m)</th></m<40lbs.<>	Front, Rear, Left, Right, B ed for shipment ck/face. ion: 30G's. Test also at 40 inch-per-second) for prod) and 50G's to find luct mass (m)	
	Non-operating shock	 i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired. ii. Trapezoidal Shock- Transportation Environment, Non-Operation 			
	Operating shock	N/A			
	Non-operating humidity	10% to 90% (non-conden	ising at ambient)		
	Operating humidity	N/A			
	Non-operating temperature	-30° C to 95° C			
	Operating temperature	10° to 90° C			
	Key-leveling mechanisms	N/A			
	Key structure type	Tact Switch			
Mechanical	Key life	1million cycles			
	Key actuation	75±20g			
	Keycaps	0.3mm key travel			



HP 655	5 wireless Mouse
--------	------------------

HP 655 wireless Mouse			
Dimensions (H x L x W)	4.74 x 2.75 x 1.63 in (120.29 x 69.97 x41.39 mm)		
Weight	0.194lb (88g)		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Operating voltage	3 VDC, +/-5%	
	Power consumption (typical)	10 mA Max	
	Resolution	1,200 DPI (Default)	
	Sensor	Pixart PAW3222DB-TJDS	
	Tracking speed	10G(max), 1G=9.8m/s2	
	Tracking acceleration	2.4GHz Wireless	
Mechanical	Color	Jack Black	
Regulatory approvals	Compliant	CB, CE, FCC, CULus, ICES, IC, TRC, TRA, ICASA, UA, EAC, CNC, ANATEL, NOM-NYCE SCT, IFETEL, MPTC, RCM, PosTel, VCCI, TELEC, KC, MCMC, IDA, BSMI, NCC, DWLF&M, TP-BY, MOC	
Ergonomic compliance	Compliant	TUVGS	

HP PS/2 Mouse			
Dimensions (H x L x W)	4.53 x 2.48 x1.46 in (115.2x 63 x37 mm)		
Weight	0.22lb (101.6g)		
Environmental	Operating temperature	41° to 122° F (5° to 50° C)	
	Non-operating temperature	(-4° to 140° F) (-20° to 60° C)	
	Operating humidity	10% to 85% (non-condensing at ambient)	
	Non-operating humidity	5% to 95% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
	System interface	PS/2	
Mechanical	Switch actuation	60±15g nominal peak force with tactile feedback	
	Switch life	3 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	



QuickSpecs

Technical Specifications – Input/Output Devices

	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	

HP USB 125 (Antimicrobial)/128 Laser Mouse (China only)

Dimensions (H x L x W)	112 x 63 x 36.2 mm (L x W x H)		
Weight	85 g		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption (typical)	100mA	
	Resolution	1,200 DPI	
	Sensor	Optical/ Laser USB mouse sensor	
	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
Mechanical	Connector	USB	
	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC	



Technical Specifications – Audio/Multimedia

AUDIO/MULTIMEDIA

Туре	Integrated
HD Stereo Codec	Realtek ALC 3252
Audio I/O Ports	Front: Headset connector supports a CTIA and OMTP style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port Rear: Line-out, Line-in*, 3.5mm and support stereo and retasking
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)

Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 5 MP Swivel Webcam with integrated dual array digital microphones

Optional integrated 5 MP Swivel Webcam + IR Sensor + Color Light Sensor with integrated dual array digital microphones (Supports Windows Hello)

Optional integrated 16MP binned Swivel Webcam + IR Sensor + Color Light Sensor + Time of Flight Sensor (TOF) (Supports Windows Hello)

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch Fingerprint matching: Performed on device Anti-Spoofing: Yes Windows Hello Support: Yes Encryption: On sensor FIPS Compliant: No



QuickSpecs

Technical Specifications – Power

POWER

HP Z1 G9 Tower Desktop PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -30°C ~65°C	
Relative Humidity	idity Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature	
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)	
80 PLUS Platinum	550W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 400Wactive PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	
Operating Voltage Range	90Vac~264Vac	
Rated Voltage Range	100Vac~240Vac	
ated Line Frequency 50HZ~60HZ		
Operating Line Frequency	perating Line Frequency 47HZ~63HZ	
Rated Input Current with Energy Efficient* Power Supply	260W Platinum≦3.1A 400W Platinum≦5.2A 550W Platinum≦6.6A	
DC Output	+12V	
1. Service parts obtained after purchase may not be low halogen.		
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	

Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.

Power Supply Fan	70mm variable speed
Power cord length	6.0 ft. (1.83 m) ²
External Power Adapter	Internal power supply
Dimensions	165mm x 95mm x 73mm
Total Cord Length	6.0 ft. (1.83 m)

1. Power cord length will be varied from different type of cords start from 1.8m.

2. The length of India power cord is 2.0m

QuickSpecs

Technical Specifications – Power

Condition	90/92/89%	Input Voltage	
10% of Rated Load	86% 115Vac/60HZ		
20% of Rated Load	90%	115Vac/60HZ	
50% of Rated Load	92%	115Vac/60HZ	
	PF>0.95		
100% of Rated Load	89%	115Vac/60HZ	
	PF>0.9	230Vac/50HZ	



Technical Specifications – Miscellaneous Features

WEIGHTS & DIMENSIONS

Chassis (W x D x H)	6.1 x 12.13 x 13.27 in	
	155 x 308 x 337 mm	
System Volume	981.9 cu in	
	16.1 L	
System Weight	13.56 lb	
	6.15 kg	
Max Supported Weight	77.16 lb	
(desktop orientation)	35 kg	
Stand Dimensions	N/A	
Packaging (W x D x H)	15.75 x 19.65 x 11.30 in	
	(400 x 499 x 287 mm)	
	MPP : 15.75 x 19.65 x 11.30 in	
	(400 x 499 x 287 mm)	
Shipping Weight	19.54 lbs (8.87 kg)	
	MPP: 20.35 lbs (9.24kg)	
Multipack	6-units per layer	
Packaging	8 layer max	
(10 units)	48 per pallet	
	47.24 x 39.37 x 95.12 in, 1200 x 1000 x 2416 mm (including pallet)	
Palletization Profile	6-units per layer	
	8 layer max	
	48 per pallet	
	47.24 x 39.37 x 95.12 in, 1200 x 1000 x 2416 mm (including pallet)	

Technical Specifications – Miscellaneous Features

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel[®] Wired for Management support; industry wide initiative to make Intel[®] architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- 1 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification

Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical)
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only)
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM

Technical Specifications – After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>Part Number</u>
NVIDIA® T400 2GB GDDR6 3mDP	340K8AA
NVIDIA® T400 4GB GDDR6 3mDP	5Z7E0AA
HP DisplayPort to HDMI True 4k Adapter	2JA63AA
HP DVI Cable Kit	DC198A
HP HDMI Standard Cable Kit	T6F94AA
HP DisplayPort to VGA Adapter	AS615AA
HP DisplayPort to DVI-D Adapter	FH973AA
HP USB-C To DisplayPort Adapter	N9K78AA
Data Storage Drives	
HP PCIe NVME TLC M.2 256GB SSD	1CA51AA
HP PCIe NVME TLC M.2 512GB SSD	X8U75AA
HP PCIe Gen 4 NVME TLC M.2 512GB SSD	406L8AA
HP PCIe Gen 4 NVME TLC M.2 1TB SSD	406L7AA
HP 500GB 7200PRM SATA 3.5" Hard Drive	QK554AA
HP 1TB 7200rpm SATA 3.5" Hard Drive	QK555AA
Input Devices	
HP 125 Wired Keyboard	266C9AA
HP 225 Antimicrobial Wired Mouse and Keyboard Combo (China only)	286K3AA
HP 225 Wired Mouse and Keyboard Combo	286J4AA
HP 125 Wired Mouse	265A9AA
HP 128 Laser Wired Mouse	265D9AA
HP Wired Desktop 320K Keyboard	9SR37AA
HP Wired Desktop 320M Mouse	9VA80AA
HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
HP USB Business Slim CCID SmartCard Keyboard	Z9H48AA
HP 655 Wireless Keyboard and Mouse Combo	4R009AA
HP 455 Programmable Wireless Keyboard	4R177AA
HP USB Keyboard and Mouse Healthcare Edition ¹	1VD81AA
1. Only available in NA/EMEA regions	
System Memory	Part Number
HP 8GB DDR5-4800 UDIMM	4M9X9AA
HP 16GB DDR5-4800 UDIMM	4M9Y0AA
HP 32GB DDR5-4800 UDIMM	4M9Y2AA
Multimedia Devices	Part Number



Technical Specifications – After Market Options

HP S101 Speaker Bar	5UU40AA
HP Stereo 3.5mm Headset G2	428K7AA
HP Stereo USB Headset G2	428K6AA
HyperX Cloud MIX – Gaming Headset (Black-Gunmetal)	4P5K9AA
HyperX Cloud Flight – Wireless Gaming Headset (Black-Red)	4P5L4AA
HyperX Cloud Stinger Core – Gaming Headset (Black)	4P4F4AA
HyperX Cloud Core + 7.1 Gaming Headset (Black)	4P4F2AA
HyperX SoloCast USB WHT Microphone (Black)	4P5P8AA
Security Devices	Part Number
HP Business PC Security Lock v3 Kit	3XJ17AA
HP Keyed Cable Lock 10mm	T1A62AA
HP Master Keyed Cable Lock 10mm	T1A63AA
HP Sure Key Cable Lock	6UW42AA
I/O Devices	Part Number
HP DisplayPort Port Flex IO v2	13L54AA
HP Type-C [®] USB 3.1 Gen2 Port Flex IO v2	13L59AA
HP USB 3.1 Gen1 x2 Module Flex IO v2	13L58AA
HP VGA Port Flex IO v2	13L53AA
HP Serial Port Flex IO v2	13L56AA
HP Internal Serial Port (in rear wall)	3TK82AA
HP PCIe x1 Parallel Port Card	N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)	1VD82AA
HP USB to Serial Port Adapter	J7B60AA
HP USB-C to Display Port Adapter	N9K78AA
HP USB Type-C Extension Cable Kit (5M)	<u>9JH45AA</u>
HP Serial Port v3 Flex IO	<u>58895AA</u>
HP HDMI Port Flex IO v2	<u>13L55AA</u>
HP Parallel Port Adapter	<u>KD061AA</u>
NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is:	
http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607	
Communication Devices	<u>Part Number</u>
Intel® Ethernet I225-T1 GbE NIC	<u>406L9AA</u>

© Copyright 2024 HP Development Company, L.P.

The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. Microsoft and Windows are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Celeron, Core, Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth[®] is a trademark of its proprietor, used by HP, Inc. under license. USB Type-C[®] and USB-C[®] are trademarks of USB Implementers Forum. NVIDIA, GeForce and NVS are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency. DisplayPort[™] and the DisplayPort[™] logo are trademarks owned by the Video Electronics Standards Association (VESA[®]) in the United States and other countries.

Date	Version History	Action	Description of Change
March 16, 2022	From v1 to v2	Changed	Social and Environmental Responsibility section
June 1, 2022	From v2 to v3	Changed	Graphics section
July 1, 2022	From v3 to v4	Changed	Graphics and AFTER MARKET OPTIONS sections
October 1, 2022	From v4 to v5	Changed	AFTER MARKET OPTIONS section
December 7, 2022	From v5 to v6	Changed	Format
December 15, 2022	From v6 to v7	Changed	GRAPHICS section
March 1, 2023	From v7 to v8	Changed	Manageability section
March 30, 2023	From v8 to v9	Changed	Processors section
April 25, 2023	From v9 to v10	Changed	STORAGE, POWER, CERTIFICATION AND COMPLIANCE sections
May 1, 2023	From v10 to v11	Changed	AFTER MARKET OPTIONS section
May 22, 2023	From v11 to v12	Changed	GRAPHICS section
June 1, 2023	From v12 to v13	Changed	Image page 2, GRAPHICS, PROCESSORS sections
July 1, 2023	From v13 to v14	Changed	Format page 1
December 1, 2023	From v14 to v15	Changed	Social and Environmental Responsibility section
February 1, 2024	From v15 to v16	Changed	ENVIRONMENTAL & INDUSTRY section
March 1, 2024	From v16 to v17	Changed	Networking and Communications
March 18, 2024	From v17 to v18	Changed	Processors section

